



**Statement of Materials, Construction**

LEAD-FREE -- 28L PLCC -- TABLE OF MATERIAL DECLARATION								
No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element/Compound)	CAS Number	Material Mass (grams)	Material Weight % (of Total Pkg.)	Material Weight % (of Component)
1	Leadframe	Copper Alloy (with silver plating)	0.17847	Cu	7440-50-8	0.17793	16.64	99.70
				Zr	7440-67-7	0.00018	0.02	0.10
				Silver Plating	7440-22-4	0.00036	0.03	0.20
2	Die	Silicon Chip	0.00364	Si	7440-21-3	0.00363	0.34	99.99
3	Die Attach Material	Conductive Epoxy	0.00057	Silver (Ag)	7440-22-4	0.00043	0.04	75.00
				Epoxy Resin	9003-36-5	0.00009	0.01	16.00
				Diluent	26647-14-3	0.00005	0.00	8.00
				Dicydiamide	461-58-5	0.00001	0.00	1.00
4	Wire	Gold	0.00076	Au	7440-57-5	0.00076	0.07	99.99
5	Lead Finish	Tin	0.01500	Sn	7440-31-5	0.01500	1.40	100
6	Encapsulation	Epoxy Resin	0.87095	Fused Silica	60676-86-0	0.70982	66.38	81.50
				Epoxy Resin	Proprietary	0.08710	8.14	10.00
				Phenol Resin	Proprietary	0.06968	6.52	8.00
				Carbon Black	1333-86-4	0.00435	0.41	0.50
Total Package Weight =			1.06938					

**Note:** Component Weight based on assembly of generic parts.

**Conclusion:**

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (ppm)	Maximum Allowable Limit (wt %)
Lead	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%